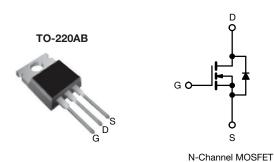
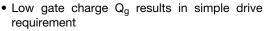


Power MOSFET



| PRODUCT SUMMAI | RY | |
|--------------------------|------------------------|-----|
| V _{DS} (V) | 60 | 00 |
| $R_{DS(on)}(\Omega)$ | V _{GS} = 10 V | 2.2 |
| Q _g max. (nC) | 2 | 3 |
| Q _{gs} (nC) | 5. | .4 |
| Q _{gd} (nC) | 1 | 1 |
| Configuration | Sin | gle |

FEATURES





 Improved gate, avalanche, and dynamic dV/dt ruggedness

- · Fully characterized capacitance and avalanche voltage and current
- Effective Coss specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptable power supply
- · High speed power switching

TYPICAL SMPS TOPOLOGY

Single Transistor flyback

| ORDERING INFORMATION | |
|---------------------------------|-----------------|
| Package | TO-220AB |
| Lead (Pb)-free | IRFBC30APbF |
| Lead (Pb)-free and halogen-free | IRFBC30APbF-BE3 |

| ABSOLUTE MAXIMUM RATINGS (T_C | = 25 °C, unl | ess otherwis | se noted) | | | |
|-----------------------------------------------------------|-------------------------|-------------------------------------------------------------------------|-----------------------------------|-------------|----------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | | V_{DS} | 600 | | |
| Gate-source voltage | | | V_{GS} | ± 30 | V | |
| Continuous dusin surrent | V at 10 V | $T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$ | | 3.6 | | |
| Continuous drain current | V _{GS} at 10 V | T _C = 100 °C | I _D | 2.3 | Α | |
| Pulsed drain current a | | | I _{DM} | 14 | | |
| Linear derating factor | | | | 0.69 | W/°C | |
| Single pulse avalanche energy ^b | | | E _{AS} | 290 | mJ | |
| Repetitive avalanche current a | | | I _{AR} | 3.6 | А | |
| Repetitive avalanche energy ^a | | | E _{AR} | 7.4 | mJ | |
| Maximum power dissipation $T_C = 25 ^{\circ}C$ | | P_{D} | 74 | W | | |
| Peak diode recovery dV/dt ^c | dV/dt | 7.0 | V/ns | | | |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | | |
| Soldering recommendations (peak temperature) ^d | For 10 s | | - | 300 | °C | |
| Mary all and a second | 6-32 or M3 screw | | | 10 | lbf ⋅ in | |
| Mounting torque | 0-32 Of I | NIO SCIEW | | 1.1 | N⋅m | |

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11) b. Starting T_J = 25 °C, L = 41 mH, R_g = 25 Ω , I_{AS} = 3.6 A (see fig. 12) c. I_{SD} \leq 3.6 A, dI/dt \leq 170 A/µs, V_{DD} \leq V_{DS}, T_J \leq 150 °C

- d. 1.6 mm from case



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| THERMAL RESISTANCE RAT | INGS | | | |
|-------------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R _{thJA} | - | 62 | |
| Case-to-sink, flat, greased surface | R _{thCS} | 0.50 | - | °C/W |
| Maximum junction-to-case (drain) | R _{thJC} | - | 1.7 | |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|-----------------------------------------------|-----------------------|---------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|----------|-----------|-----------|------|
| Static | | | | | | | |
| Drain-source breakdown voltage | V_{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 600 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | Reference to 25 °C, I _D = 1 mA | | 0.67 | - | V/°C |
| Gate-source threshold voltage | V _{GS(th)} | V _{DS} = | V _{GS} , I _D = 250 μA | 2.0 | - | 4.5 | V |
| Gate-source leakage | I _{GSS} | , | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 100 | nA |
| 7 | I _{DSS} | V _{DS} = | V _{DS} = 600 V, V _{GS} = 0 V | | - | 25 | μА |
| Zero gate voltage drain current | | V _{DS} = 480 V | V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C | | - | 250 | |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 2.2 A ^b | - | - | 2.2 | Ω |
| Forward transconductance | 9 _{fs} | V _{DS} = | 50 V, I _D = 2.2 A ^b | 2.1 | - | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | $V_{GS} = 0 V$, | | - | 510 | - | |
| Output capacitance | C _{oss} | | $V_{DS} = 25 \text{ V},$ | - | 70 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1. | f = 1.0 MHz, see fig. 5 | | 3.5 | - | 1 _ |
| Outrat annuitance | C _{oss} | V _{GS} = 0 V | $V_{DS} = 1.0 \text{ V}, f = 1.0 \text{ MHz}$ | - | 730 | - | pF |
| Output capacitance | | | $V_{DS} = 480 \text{ V}, f = 1.0 \text{ MHz}$ | - | 19 | - | |
| Effective output capacitance | C _{oss} eff. | | V _{DS} = 0 V to 480 V ^c | - | 31 | - | |
| Total gate charge | Q_g | | | - | - | 23 | |
| Gate-source charge | Q_{gs} | $V_{GS} = 10 \text{ V}$ | I _D = 3.6 A, V _{DS} = 480 V see fig. 6 and 13 ^b | - | - | 5.4 | nC |
| Gate-drain charge | Q_{gd} | | see lig. o and 10 | - | - | 11 | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 300 V, I _D = 3.6 A, | | - | 9.8 | - | - ns |
| Rise time | t _r | | | - | 13 | - | |
| Turn-off delay time | t _{d(off)} | $R_g = 12 \Omega$, | R_g = 12 Ω , R_D = 82 Ω , see fig. 10 b | | 19 | - | |
| Fall time | t _f | 1 | | - | 12 | - | |
| Gate input resistance | R_g | f = 1 MHz, open drain | | 0.8 | - | 4.6 | Ω |
| Drain-Source Body Diode Characteristic | cs | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 3.6 | A |
| Pulsed diode forward current ^a | I _{SM} | | | - | - | 14 | |
| Body diode voltage | V_{SD} | $T_J = 25 ^{\circ}\text{C}, I_S = 3.6 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$ | | - | - | 1.6 | V |
| Body diode reverse recovery time | t _{rr} | - T _J = 25 °C, I _F = 3.6 A, dl/dt = 100 A/µs b | | - | 400 | 600 | ns |
| Body diode reverse recovery charge | Q _{rr} | | | - | 1.1 | 1.7 | μC |
| Forward turn-on time | t _{on} | Intrinsic tu | rn-on time is negligible (turn | on is do | minated b | ov Ls and | Ln) |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%$
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

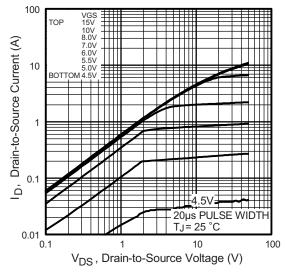


Fig. 1 - Typical Output Characteristics

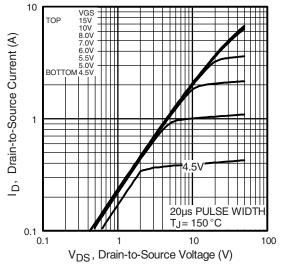


Fig. 2 - Typical Output Characteristics

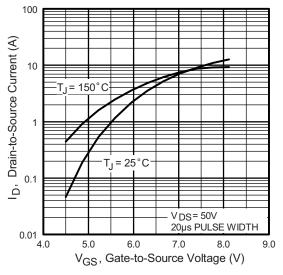


Fig. 3 - Typical Transfer Characteristics

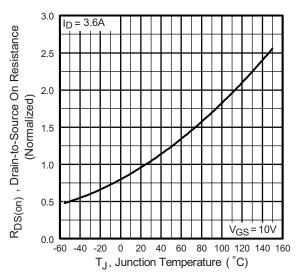


Fig. 4 - Normalized On-Resistance vs. Temperature



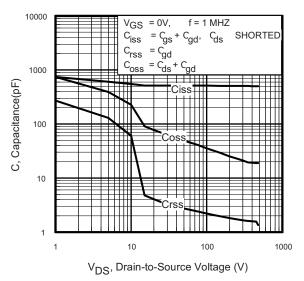


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

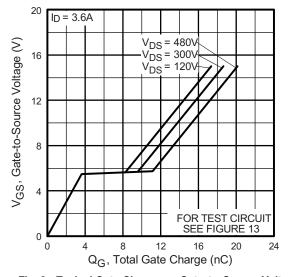


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

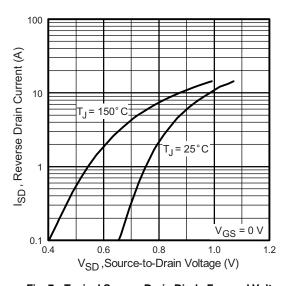


Fig. 7 - Typical Source-Drain Diode Forward Voltage

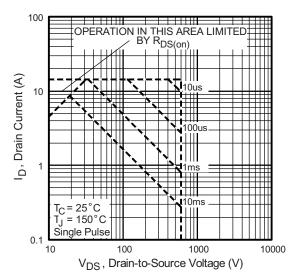


Fig. 8 - Maximum Safe Operating Area



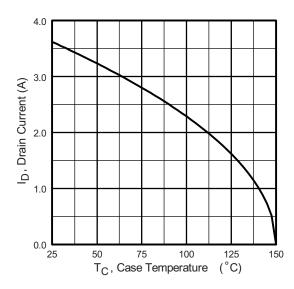


Fig. 9 - Maximum Drain Current vs. Case Temperature

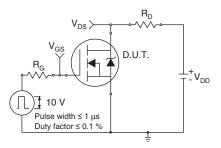


Fig. 10a - Switching Time Test Circuit

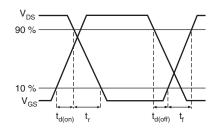


Fig. 10b - Switching Time Waveforms

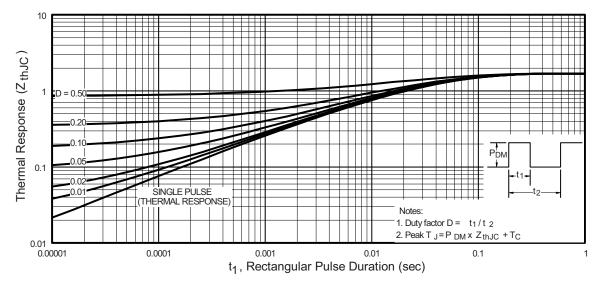


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

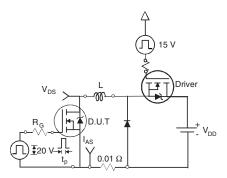


Fig. 12a - Unclamped Inductive Test Circuit

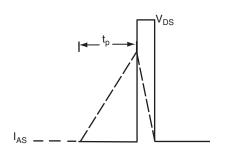


Fig. 12b - Unclamped Inductive Waveforms

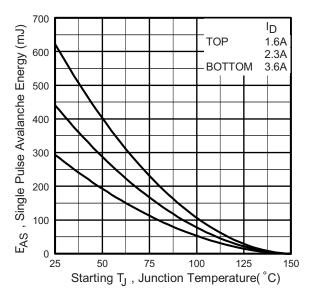


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

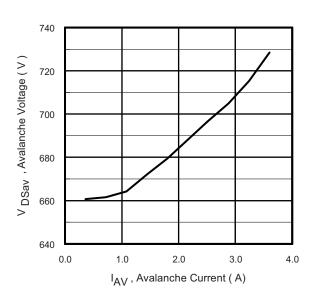


Fig. 12d - Typical Drain-to-Source Voltage vs.
Avalanche Current

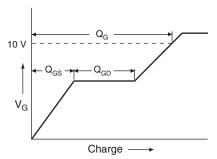


Fig. 13a - Basic Gate Charge Waveform

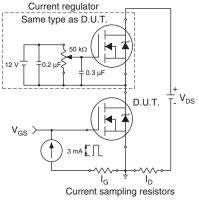
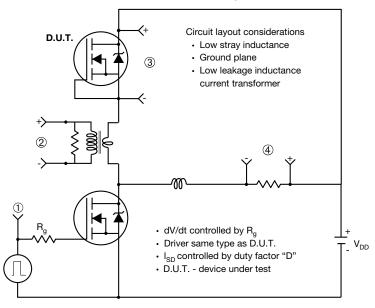


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



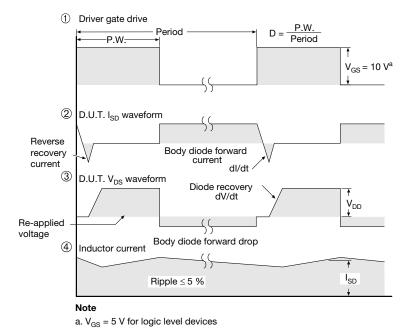
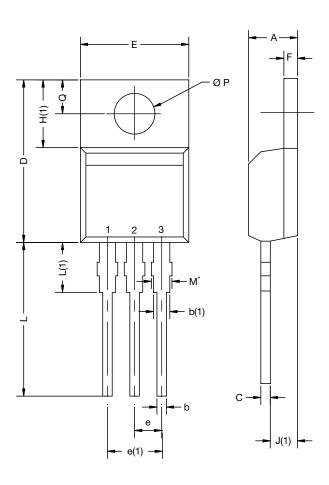


Fig. 14 - For N-Channel

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TO-220-1



| DIM. | MILLIM | IETERS | INC | HES |
|------|--------|--------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| Α | 4.24 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.02 | 0.027 | 0.040 |
| b(1) | 1.14 | 1.78 | 0.045 | 0.070 |
| С | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.33 | 15.85 | 0.564 | 0.624 |
| Е | 9.96 | 10.52 | 0.392 | 0.414 |
| е | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.10 | 6.71 | 0.240 | 0.264 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.36 | 14.40 | 0.526 | 0.567 |
| L(1) | 3.33 | 4.04 | 0.131 | 0.159 |
| ØΡ | 3.53 | 3.94 | 0.139 | 0.155 |
| Q | 2.54 | 3.00 | 0.100 | 0.118 |

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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